RELIABILITY REPORT

FOR

MAX4603EWE+

PLASTIC ENCAPSULATED DEVICES

March 2, 2015

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX4603EWE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX4601/MAX4602/MAX4603 quad analog switches feature low on-resistance of 2.5 max. On-resistance is matched between switches to 0.5 max and is flat (0.5 max) over the specified signal range. Each switch can handle rail-to-rail analog signals. The off-leakage current is only 2.5nA maximum at TA = +85°C. These analog switches are ideal in low-distortion applications and are the preferred solution over mechanical relays in automatic test equipment or applications where current switching is required. They have low power requirements, require less board space, and are more reliable than mechanical relays. The MAX4601 has four normally closed (NC) switches, the MAX4602 has four normally open (NO) switches, and the MAX4603 has two NC and two NO switches. These switches operate from a single supply of +4.5V to +36V or from dual supplies of ±4.5V to ±20V. All digital inputs have +0.8V and +2.4V logic thresholds, ensuring TTL/CMOS-logic compatibility when using ±15V or a single +12V supply.

II. Manufacturing Information

A. Description/Function:	2.5Ω, Quad, SPST, CMOS Analog Switches
B. Process:	S5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Malaysia
F. Date of Initial Production:	November 13, 1998

III. Packaging Information

A. Package Type:	16-pin SOIC (W)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0060
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	105°C/W
K. Single Layer Theta Jc:	22°C/W
L. Multi Layer Theta Ja:	69.1°C/W
M. Multi Layer Theta Jc:	22°C/W

IV. Die Information

A. Dimensions:	140X163 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad \text{(Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 13.7 \times 10^{-9}$

λ = 13.7 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S5 Process results in a FIT Rate of 0.09 @ 25C and 1.53 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot XY9CBN018A, D/C 9914)

The AH18-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-3000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1

Reliability Evaluation Test Results

MAX4603EWE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	XYPCBN018D, D/C 9918

Note 1: Life Test Data may represent plastic DIP qualification lots.